

PRODUCT FEATURES

- IGBT CHIP(Trench+Field Stop technology)
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability
- Fast switching and short tail current
- Free wheeling diodes with fast and soft reverse recovery
- Low switching losses

APPLICATIONS

- High frequency switching application
- Medical applications
- Motion/servo control
- UPS systems



IGBT

ABSOLUTE MAXIMUM RATINGS($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
V_{CES}	Collector Emitter Voltage	$T_J=25^\circ\text{C}$	1200	V
V_{GES}	Gate Emitter Voltage		± 20	
I_C	DC Collector Current	$T_C=25^\circ\text{C}, T_{Jmax}=175^\circ\text{C}$	630	A
		$T_C=90^\circ\text{C}, T_{Jmax}=175^\circ\text{C}$	450	
I_{CM}	Repetitive Peak Collector Current	$tp=1\text{ms}$	900	
P_{tot}	Power Dissipation Per IGBT	$T_C=25^\circ\text{C}, T_{Jmax}=175^\circ\text{C}$	2142	W

Diode

ABSOLUTE MAXIMUM RATINGS ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
V_{RRM}	Repetitive Reverse Voltage	$T_J=25^\circ\text{C}$	1200	V
$I_{F(AV)}$	Average Forward Current		400	A
I_{FRM}	Repetitive Peak Forward Current	$tp=1\text{ms}$	800	
I^2t		$T_J=125^\circ\text{C}, t=10\text{ms}, V_R=0\text{V}$	39.2	KA^2S

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MMG450D120UA6TC

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ELECTRICAL CHARACTERISTICS ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit	
$V_{GE(th)}$	Gate Emitter Threshold Voltage	$V_{CE}=V_{GE}, I_C=18\text{mA}$	5.0	5.8	6.5	V	
$V_{CE(sat)}$	Collector - Emitter Saturation Voltage	$I_C=450\text{A}, V_{GE}=15\text{V}, T_J=25^\circ\text{C}$		1.85	2.25		
		$I_C=450\text{A}, V_{GE}=15\text{V}, T_J=125^\circ\text{C}$		2.15			
		$I_C=450\text{A}, V_{GE}=15\text{V}, T_J=150^\circ\text{C}$		2.2			
I_{CES}	Collector Leakage Current	$V_{CE}=1200\text{V}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$			1	mA	
		$V_{CE}=1200\text{V}, V_{GE}=0\text{V}, T_J=150^\circ\text{C}$			10		
I_{GES}	Gate Leakage Current	$V_{CE}=0\text{V}, V_{GE}=\pm 20\text{V}, T_J=25^\circ\text{C}$	-400		400	nA	
R_{gint}	Integrated Gate Resistor			1.4		Ω	
Q_g	Gate Charge	$V_{CE}=600\text{V}, I_C=450\text{A}, V_{GE}=15\text{V}$		2.25		μC	
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$		31.5		nF	
C_{res}	Reverse Transfer Capacitance				1.5		nF
$t_{d(on)}$	Turn on Delay Time	$V_{CC}=600\text{V}, I_C=450\text{A}$ $R_G=2.0\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$	100		ns	
			$T_J=125^\circ\text{C}$	120		ns	
			$T_J=150^\circ\text{C}$	130		ns	
t_r	Rise Time		$T_J=25^\circ\text{C}$	78		ns	
			$T_J=125^\circ\text{C}$	86		ns	
			$T_J=150^\circ\text{C}$	86		ns	
$t_{d(off)}$	Turn off Delay Time	$T_J=25^\circ\text{C}$		550		ns	
		$T_J=125^\circ\text{C}$		590		ns	
		$T_J=150^\circ\text{C}$		610		ns	
t_f	Fall Time	$T_J=25^\circ\text{C}$		120		ns	
		$T_J=125^\circ\text{C}$		200		ns	
		$T_J=150^\circ\text{C}$		220		ns	
E_{on}	Turn on Energy	$V_{CC}=600\text{V}, I_C=450\text{A}$ $R_G=2.0\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=125^\circ\text{C}$	39		mJ	
			$T_J=150^\circ\text{C}$	42		mJ	
E_{off}	Turn off Energy		$T_J=125^\circ\text{C}$	52		mJ	
			$T_J=150^\circ\text{C}$	56		mJ	
I_{SC}	Short Circuit Current		$tp_{sc} \leq 10\mu\text{S}, V_{GE}=15\text{V}$ $T_J=125^\circ\text{C}, V_{CC}=800\text{V}$		1700		A
R_{thJC}	Junction to Case Thermal Resistance (Per IGBT)				0.07	K/W	

Diode

ELECTRICAL CHARACTERISTICS ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
V_F	Forward Voltage	$I_F=400\text{A}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$		1.75	2.3	V
		$I_F=400\text{A}, V_{GE}=0\text{V}, T_J=125^\circ\text{C}$		1.5		
		$I_F=400\text{A}, V_{GE}=0\text{V}, T_J=150^\circ\text{C}$		1.45		
t_{rr}	Reverse Recovery Time	$I_F=450\text{A}, V_R=600\text{V}$ $dI_F/dt=-5300\text{A}/\mu\text{s}$ $T_J=150^\circ\text{C}$		530		ns
I_{RRM}	Max. Reverse Recovery Current			485		A
Q_{RR}	Reverse Recovery Charge			133		μC
E_{rec}	Reverse Recovery Energy			59.5		mJ
R_{thJCD}	Junction to Case Thermal Resistance (Per Diode)				0.12	K/W

MMG450D120UA6TC

MODULE CHARACTERISTICS ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions	Values	Unit	
T_{Jmax}	Max. Junction Temperature	175	$^\circ\text{C}$	
T_{Jop}	Operating Temperature	-40~150		
T_{stg}	Storage Temperature	-40~125		
V_{isol}	Isolation Breakdown Voltage	AC, 50Hz(R.M.S), t=1minute	3000	V
CTI	Comparative Tracking Index		> 225	
Torque	to heatsink	Recommended (M6)	3~5	Nm
	to terminal	Recommended (M6)	2.5~5	Nm
Weight			300	g

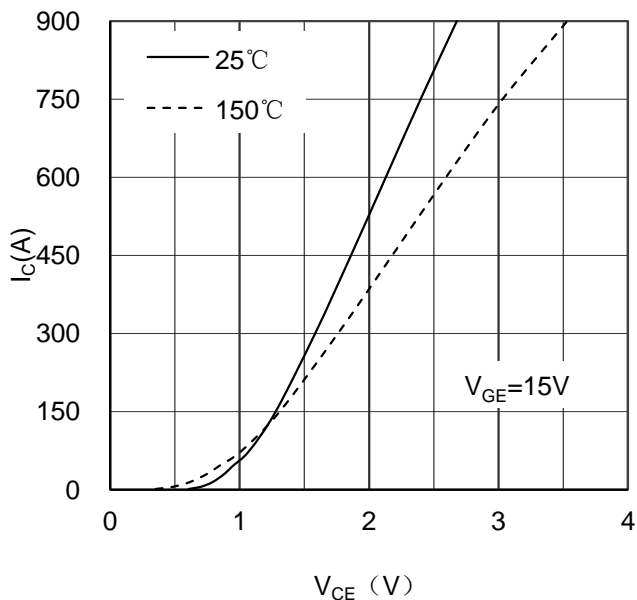


Figure 1. Typical Output Characteristics IGBT

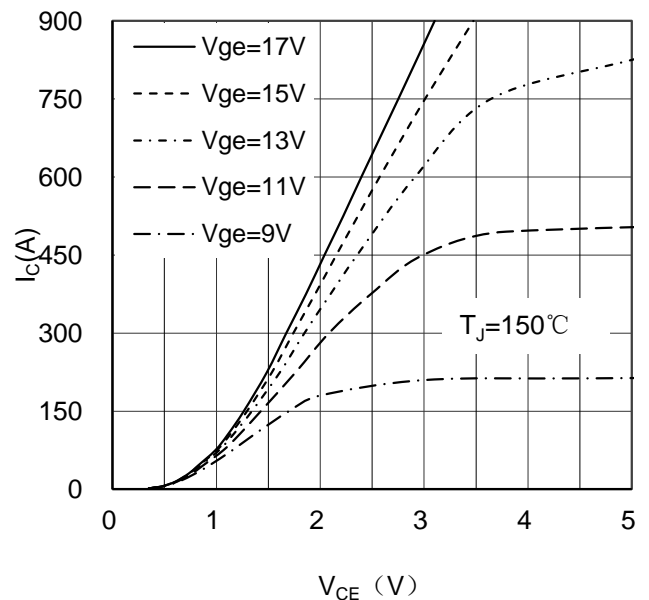


Figure 2. Typical Output Characteristics IGBT

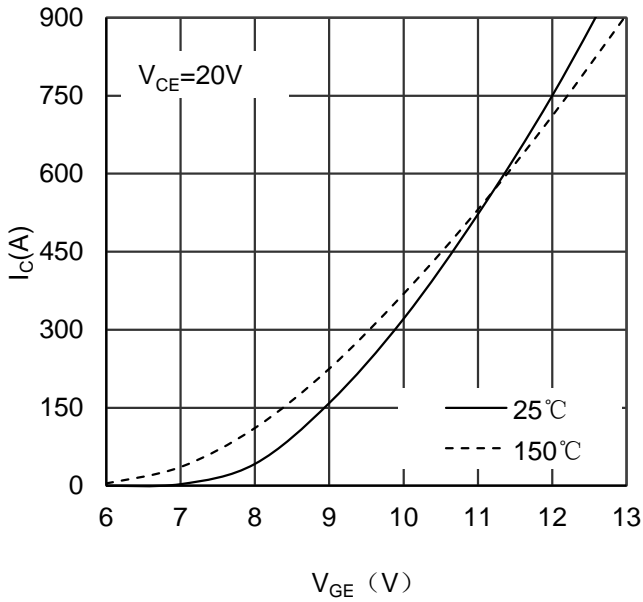


Figure 3. Typical Transfer characteristics IGBT

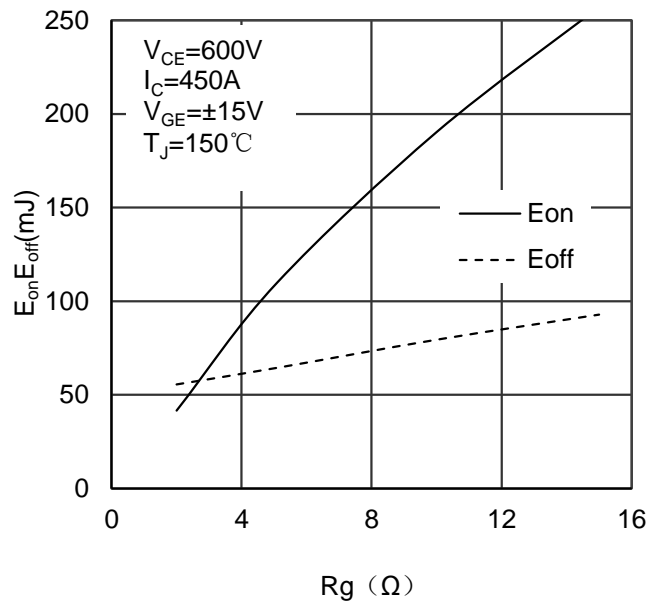


Figure 4. Switching Energy vs Gate Resistor IGBT

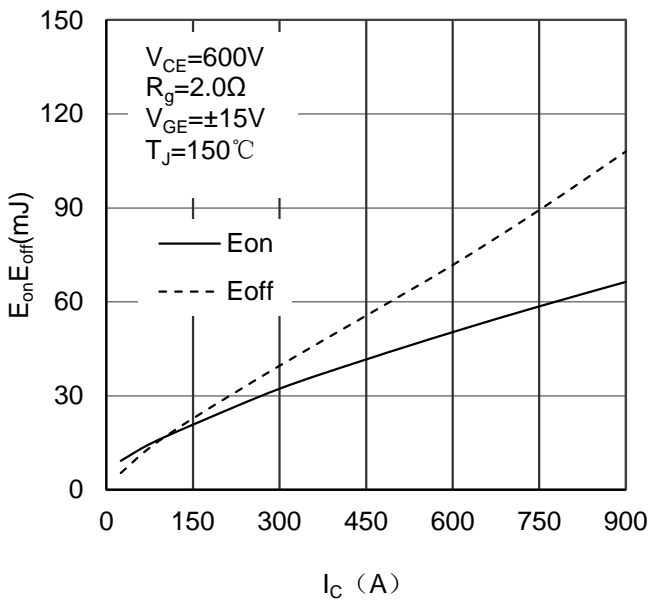


Figure 5. Switching Energy vs Collector Current IGBT

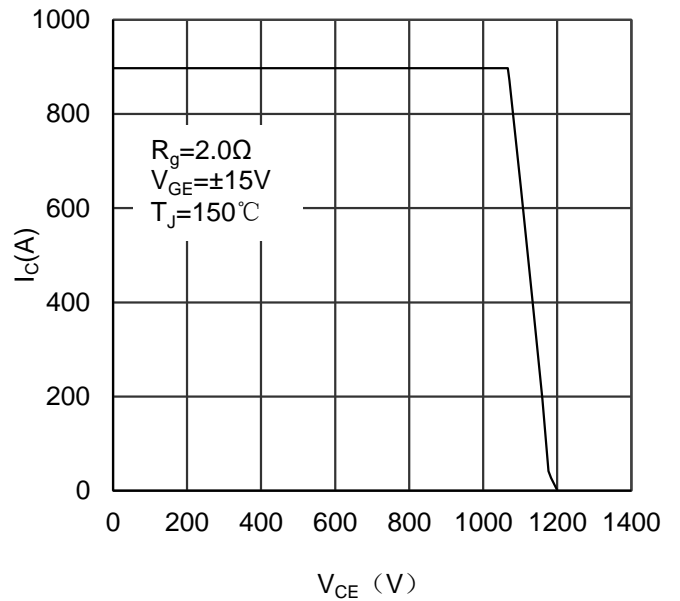


Figure 6. Reverse Biased Safe Operating Area IGBT

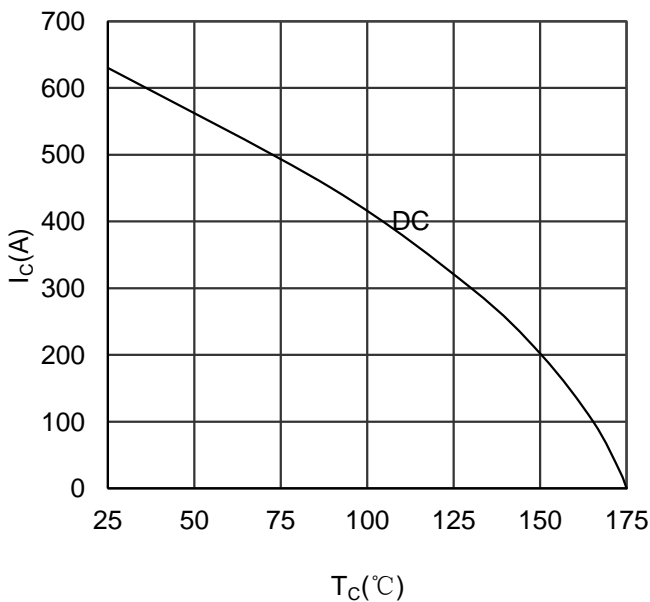


Figure 7. Collector Current vs Case temperature IGBT

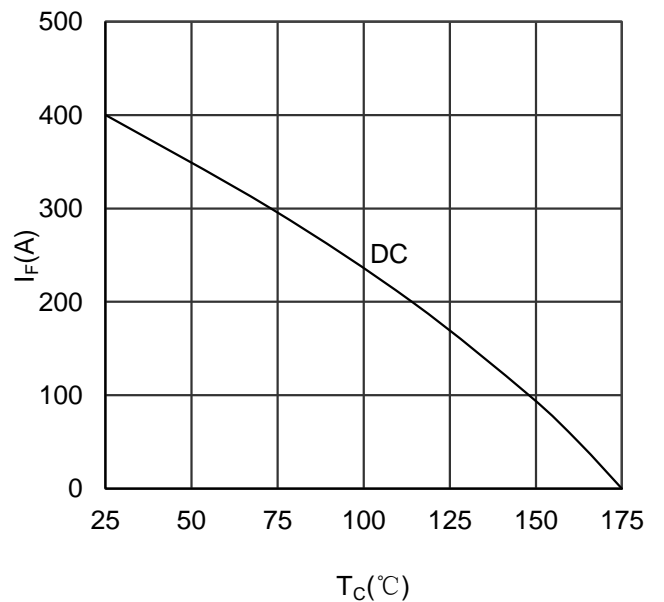


Figure 8. Forward current vs Case temperature Diode

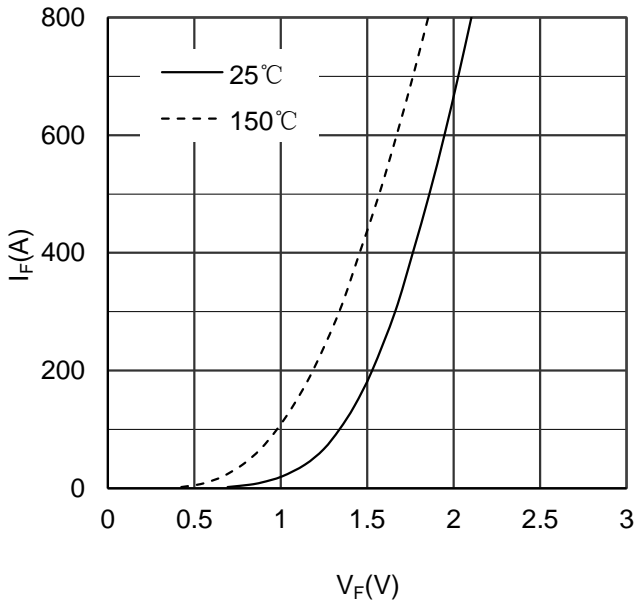


Figure 9. Diode Forward Characteristics Diode

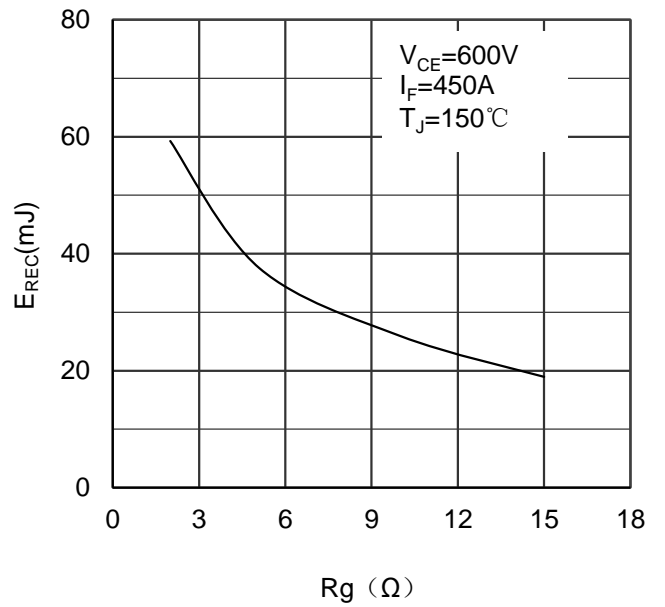


Figure 10. Switching Energy vs Gate Resistor Diode

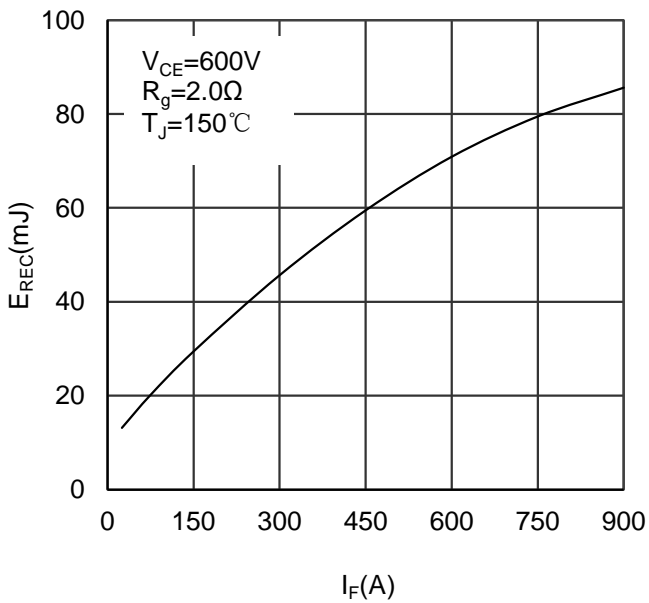


Figure 11. Switching Energy vs Forward Current Diode

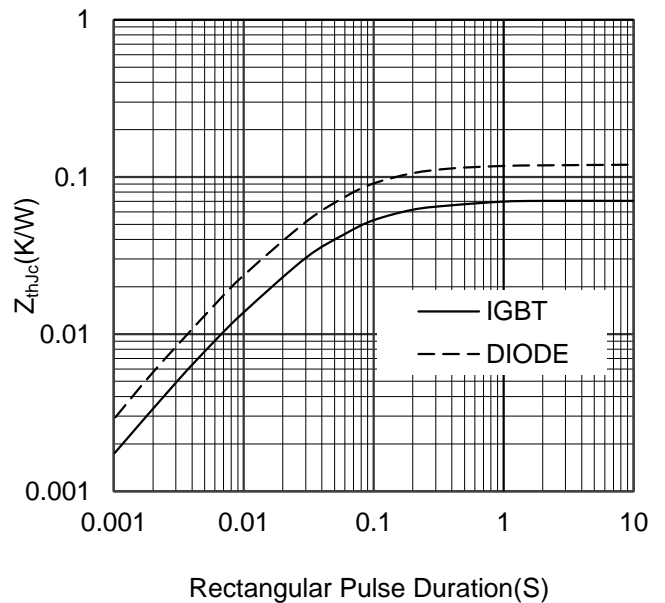


Figure 12. Transient Thermal Impedance of Diode and IGBT

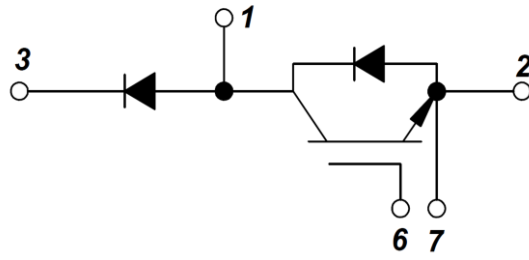
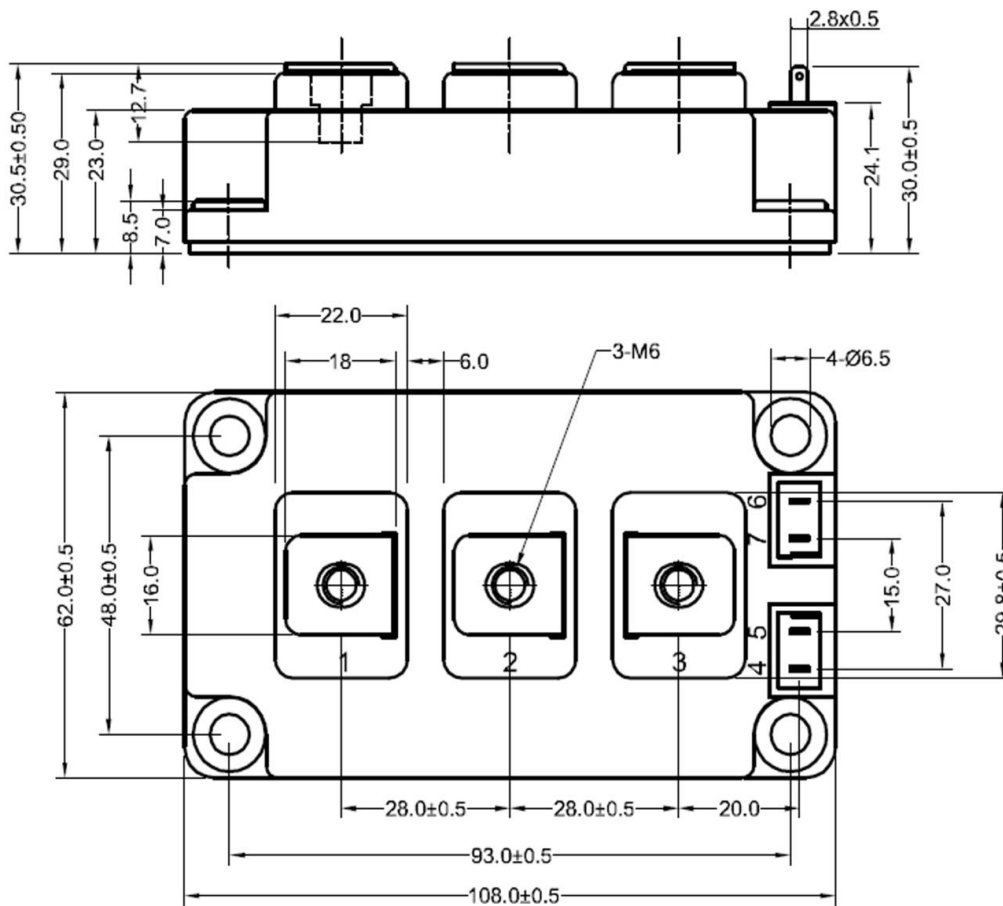


Figure 13. Circuit Diagram



Dimensions in (mm)
Figure 14. Package Outline